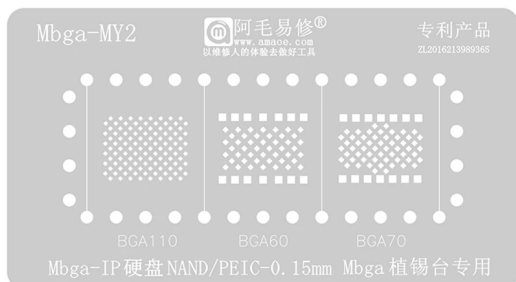


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AMAOE BGA Mbga-MY2 IP NAND/PECIC stencil reballing BGA110 BGA60 BGA70 0,15mm

Product ID: 23032

Price: **7.00 EUR**

Product weight: **0.20 kg**

Description:

AMAOE BGA Mbga-MY2 IP NAND/PECIC stencil reballing BGA110 BGA60 BGA70 0,15mm- the sieves are a product made of steel resistant to high temperatures and deformations. Precise laser-cut templates facilitate positioning during work.

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